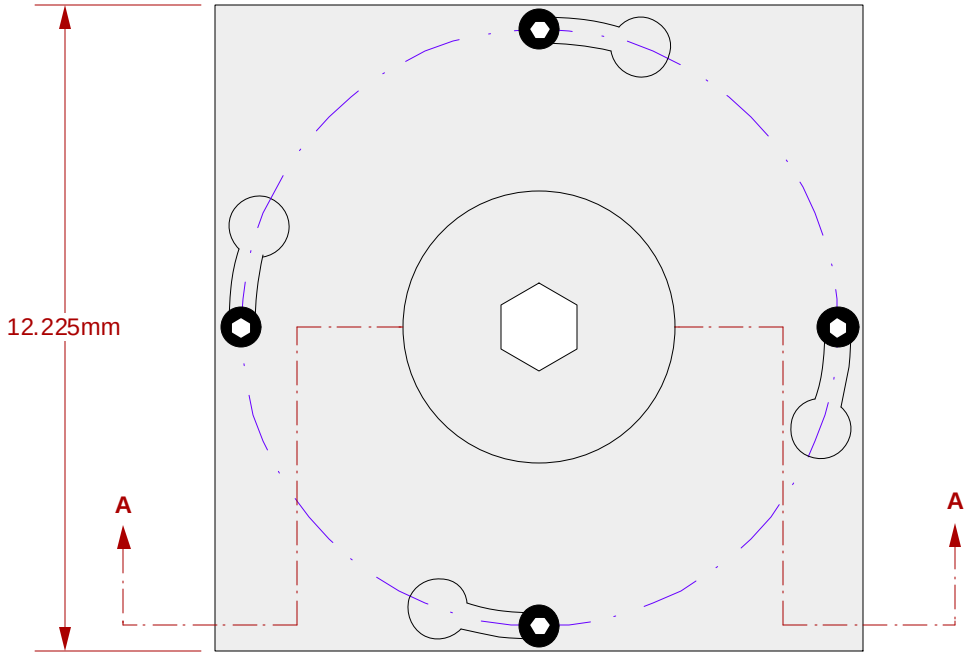
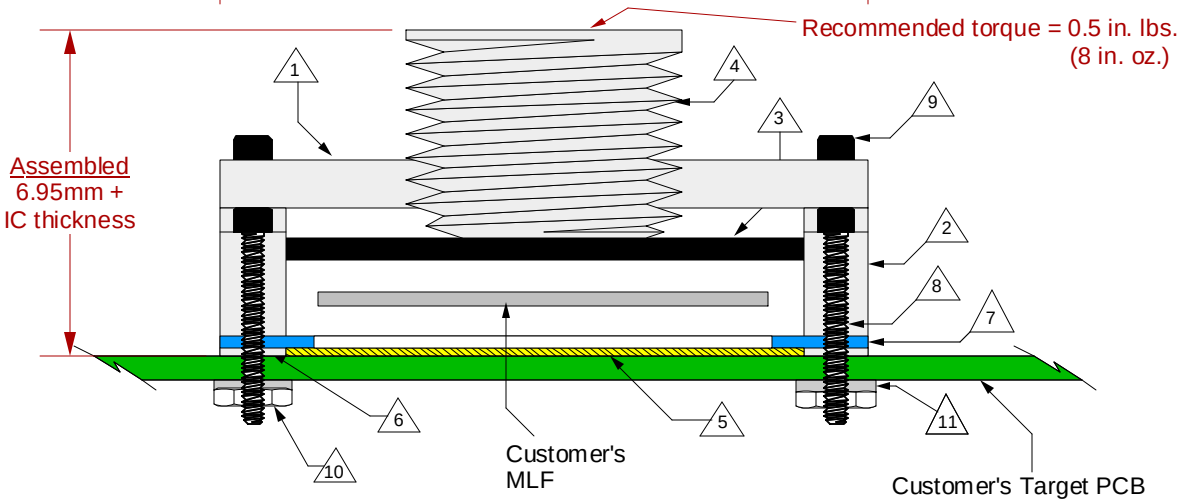
Top View



Side View
(Section AA)



GHz MLF Socket - Direct mount, solderless

Features

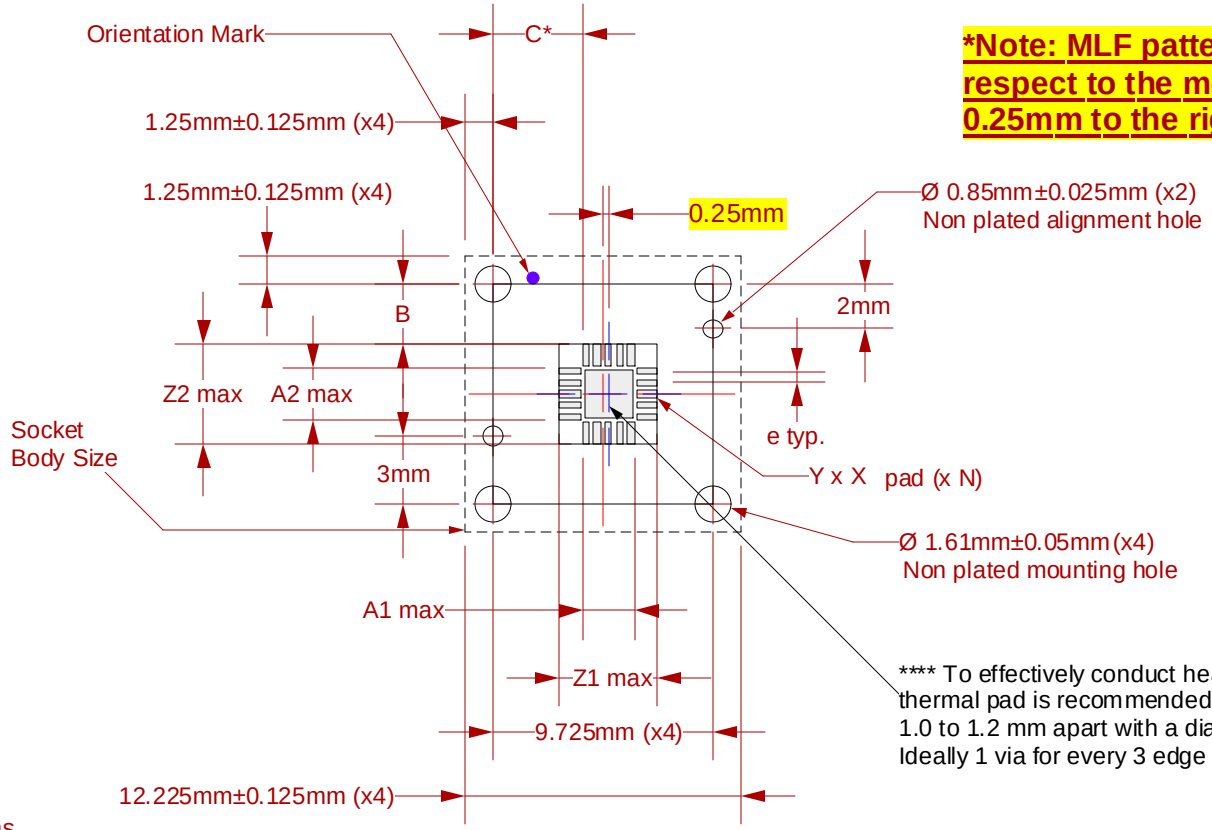
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Easily removable swivel socket lid

1	Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
2	Socket base: Black anodized Aluminum. Thickness = 3mm.
3	Compression Plate: Black anodized Aluminum. Thickness = 1.5mm.
4	Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.
5	Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
6	Elastomer Guide: Cirlex Thickness = 0.475mm.
7	IC (MLF) Guide: Ultem1000
8	Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
9	Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
10	Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
11	Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-MLF-7003 Drawing	Status: Released	Scale: -	Rev: J
 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 10/22/02	
	File: SG-MLF-7003 Dwg.mcd	Modified: 8/24/11	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



***Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**

**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm apart with a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 edge leads.

Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Package Code	C	B	Z1max	A1max	Z2max	A2 max	e	X	Y	N	Thermal Pad Recommendations
MLF12C	4.1	2.68	4.36	2.02	4.36	2.02	0.8	0.42	1.06	12	1.84 x 1.84
MLF16B	3.95	2.68	4.36	2.32	4.36	2.32	0.65	0.37	0.92	16	2.09 x 2.09
MLF20A	3.97	2.68	4.36	2.28	4.36	2.28	0.5	0.28	0.94	20	2.08 x 2.08
MLF24C	3.72	2.68	4.36	2.78	4.36	2.78	0.5	0.28	0.69	24	2.58 x 2.58
MLF24F	3.72	2.68	4.36	1.78	4.36	3.78	0.5	0.28	0.69	24	n/a
MLF28D	3.78	2.71	4.3	2.66	4.3	2.66	0.4	0.26	0.7	28	2.7 x 2.7
MLF28E	3.628	2.838	4.05	2.97	4.05	2.97	0.45	0.27	0.45	28	2.4 x 2.4
MLF32E	3.613	2.813	4.1	3	4.1	3	0.4	0.2	0.45	32	2.4 x 2.4

All dimensions are in mm.

Recommended PCB Layout Tolerances: ±0.025mm unless stated otherwise.

SG-MLF-7003 Drawing	Status: Released	Scale: 3:1	Rev: J
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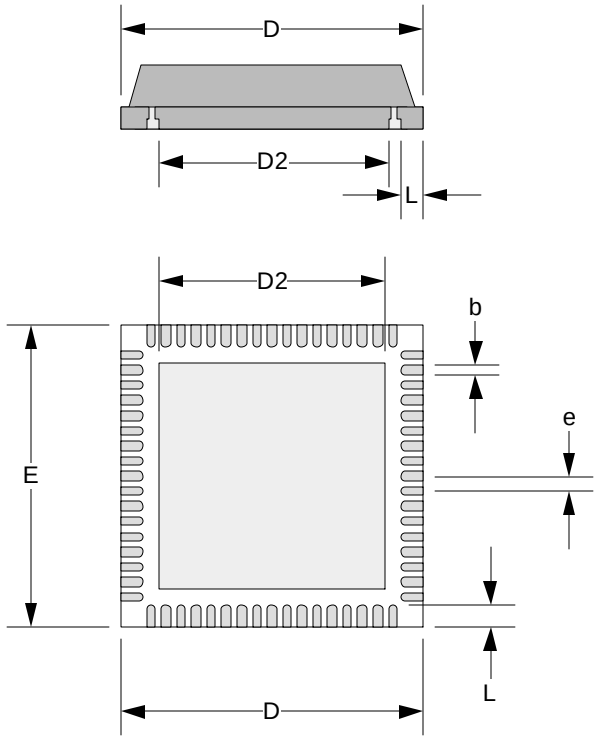

Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
MLF12C	0.8	3.85	4.15	3.85	4.15	0.28	0.4	0.5	0.75	1.94	12
MLF16B	0.65	3.85	4.15	3.85	4.15	0.23	0.35	0.5	0.75	2.22	16
MLF20A	0.5	3.85	4.15	3.85	4.15	0.18	0.3	0.5	0.75	2.18	20
MLF24C	0.5	3.85	4.15	3.85	4.15	0.18	0.3	0.3	0.5	2.68	24
MLF24F	0.5	3.9	4.1	3.9	4.1	0.2	0.3	0.35	0.45		24
MLF28E	0.45	3.95	4.05	3.95	4.05	0.17	0.27	0.35	0.45	2.4	28
MLF28D	0.4	3.95	4.05	3.95	4.05	0.17	0.25	0.35	0.45	2.08	28
MLF32E	0.4	3.85	4.15	3.85	4.15	0.15	0.25	0.3	0.5	2.4	32

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